MOS FET

FC4B22270L1

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Gate resistor installed Dual N-channel MOS FET

For lithium-ion secondary battery protection circuits

■ Features

- Low source-source ON resistance:Rss(on) typ. = 18 mΩ(VGS = 3.8 V)
- · CSP(Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL : Level 1)
- Marking Symbol: 2J

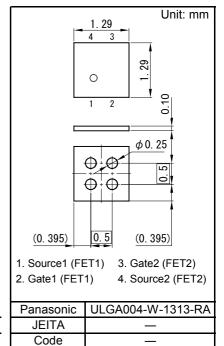
■ Packaging

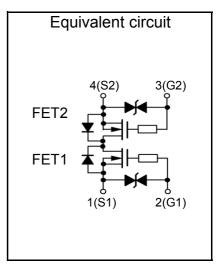
Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit	
Source-source Voltage	VSS	20	V	
Gate-source Voltage	VGS	±12	V	
Source Current (DC)	IS *1	4	А	
	IS *2	8		
Source Current (Pulsed)	ISp *2	40	Α	
Total Power Dissipation	PD *1	0.37	W	
	PD *2	1.5		
Channel Temperature	Tch	150	°C	
Storage Temperature Range	Tstg	-55 to +150	°C	
Thermal Resistance (ch-a)	Rth *1	338	°C/W	
	Rth *2	83		

- Note *1 Mounted on FR4 board ($25.4~\text{mm} \times 25.4~\text{mm} \times t1.0~\text{mm}$) using the minimum recommended pad size ($36\mu\text{m}$ Copper).
 - *2 Mounted on Ceramic substrate (70 mm \times 70 mm \times t1.0 mm).
 - *3 $t = 10 \mu s$, Duty Cycle $\leq 1 \%$





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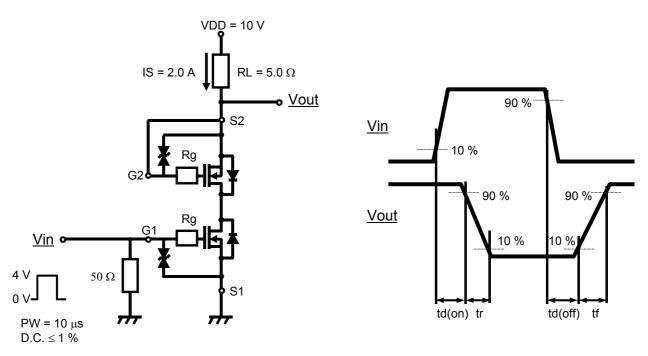
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	20			V	
Zero Gate Voltage Source Current	ISSS	VSS = 20 V, VGS = 0 V			1.0	μΑ	
Gate-source Leakage Current	IGSS	$VGS = \pm 8 \text{ V}, VSS = 0 \text{ V}$			±10	μΑ	
Gate-source Threshold Voltage	Vth	IS = 0.31 mA, VSS = 10 V	0.35	0.90	1.4	V	
Source-source On-state Resistance	RSS(on)1	IS = 2.0 A, VGS = 4.5 V	12	17	22		
	RSS(on)2	IS = 2.0 A, VGS = 3.8 V	12.5	18	23	mΩ	
	RSS(on)3	IS = 2.0 A, VGS = 3.1 V	13.5	19	26.5		
	RSS(on)4	IS = 2.0 A, VGS = 2.5 V	14	22	37		
Body Diode Forward Voltage	VF(s-s)	IF = 2.0 A, VGS = 0 V		0.8	1.2	V	
Input Capacitance *1	Ciss			910			
Output Capacitance *1	Coss	VSS = 10 V, VGS = 0 V, f = 1 KHz		105		pF	
Reverse Transfer Capacitance *1	Crss			80			
Turn-on delay Time *1,*2	td(on)	VDD = 10 V, VGS = 0 to 4.0 V		0.25		0	
Rise Time *1,*2	tr	IS = 2.0 A		0.55		μS	
Turn-off delay Time *1,*2	td(off)	VDD = 10 V, VGS = 4.0 to 0 V		1.65		0	
Fall Time *1,*2	tf	IS = 2.0 A		1.0		μS	
Total Gate Charge *1	Qg	VDD = 10 V		9			
Gate-source Charge *1	Qgs	VGS = 0 to 4.0 V,		2.6		nC	
Gate-drain Charge *1	Qgd	IS = 2.0 A		2.4			

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

- *1 Guaranteed by design, not subject to production testing
- *2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

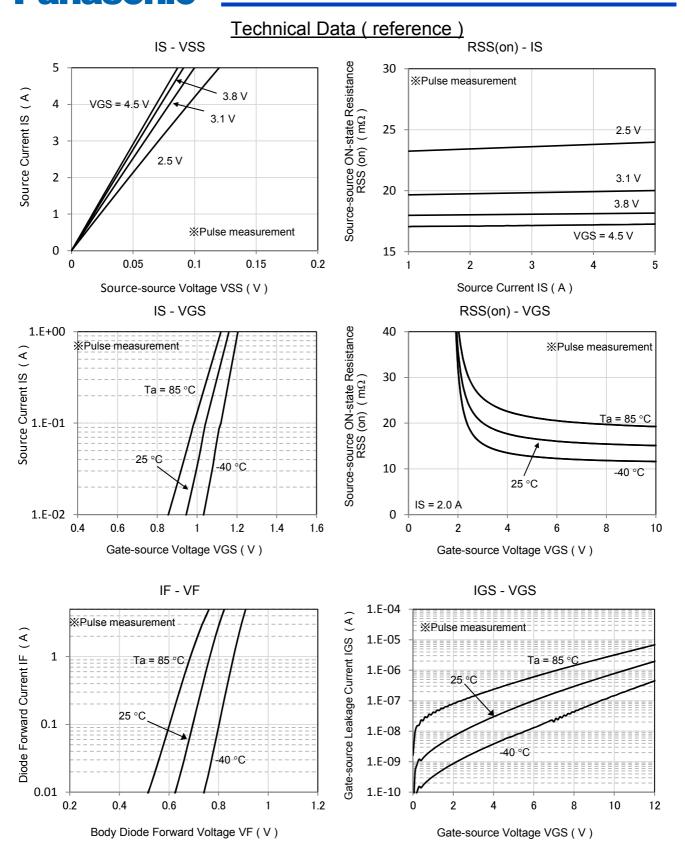
Note2:Measurement circuit



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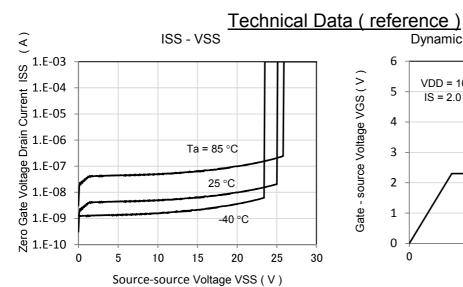


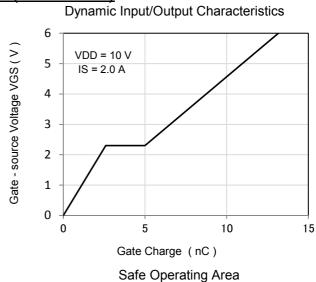
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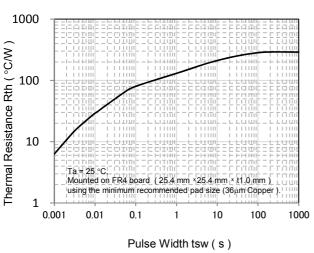
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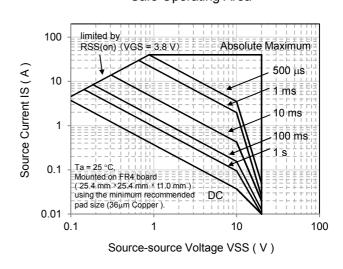
Panasonic

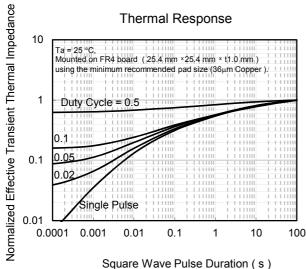






Rth - tsw





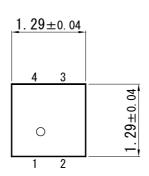
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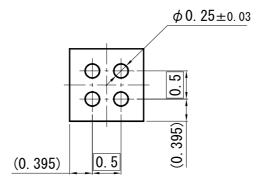
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■ Outline (ULGA004-W-1313-RA)

Unit: mm

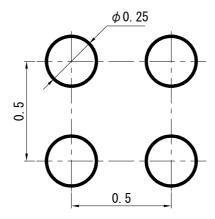






■ Land Pattern (Reference)

Unit: mm



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